PCN Number: 2019			90918002.1				N D	ate:	Sep 26, 2019			
Title: Qualification of DM		10S6 as an additional Fab site option for select devices										
Cus	stomer	Contact:		PCN Manager			Dept:			Quality Services		
Proposed 1 st Ship Date:			De	c 26, 2019	Estimated Sample Availability:			nple	Date provided at sample request.			
Change Type:												
	Assem	bly Site			Assembly Process				Assembly Materials			
Design				Electrical Specification				Mechanical Specification				
Test Site				Packing/Shipping/Labeling				Test Process				
☐ Wafer Bump Site				Wafer Bump Material				Wafer Bump Process				
			Wafer Fab Materials				Wafer	Fab Process				
				Part number change				·				
DCN Details												

Description of Change:

Texas Instruments is pleased to announce the qualification of its DMOS6 fabrication facility as an additional Wafer Fab source for the selected devices listed in the "Product Affected" section.

С	urrent Fab Site	9	Additional Fab Site				
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter		
RFAB	LBC8LV	300mm	DMOS6	LBC8LV	300mm		

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

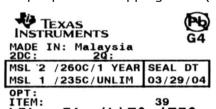
None

Changes to product identification resulting from this PCN:

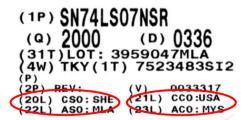
Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City		
RFAB	RFB	USA	Richardson		
DMOS6	DM6	USA	Dallas		

Sample product shipping label (not actual product label)







Product Affected:

LM36272YFFR	LM36273YFFR	LM36274YFFR							

Qualification Report

Approve Date 6-Sept-2019

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: LM36274YFFR	QBS Product Reference: LM36274YFFR	QBS Product Reference: LM3631YFFR	QBS Product Reference: LM3632YFFR	QBS Product Reference: LM36923YFF	QBS Process Reference: TAS2552YFFR	QBS Process Reference: TAS2553YFFR	QBS Package Reference (BUMP): BQ25898CYFFR	QBS Package Reference(BUMP): DRV2605YZFR	QBS Package Reference(Back- end): TPS623800YFFR
AC	Autoclave 121C	96 Hours	-	-	-	-	-	-	-	-	-	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/30/0	1/30/0	2/60/0	1/30/0	-	-	1/15/0	1/15/0	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	1/305/0	-	-	-	3/3000/0	-	-	-
CDM	ESD - CDM	1000 V	1/3/0	2/6/0	-	2/6/0	-	-	-	-	-	-
CDM	ESD - CDM	1500 V	1/3/0	2/6/0	-	2/6/0	1/3/0	-	-	-	-	-
HBM	ESD - HBM	2000 V	1/3/0	2/6/0	-	2/6/0	1/3/0	-	-	3/9/0	1/3/0	-
HBM	ESD - HBM	2500 V	1/3/0	2/6/0	-	2/6/0	1/3/0	-	-	-	-	-
FTY	Test Yield Summary	-	-	1/Pass	-	-	-	-	-	-	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	1/66/0	-	-	3/231/0	-	-	3/231/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	-	-	-	-	3/228/0	-	3/231/0	3/231/0	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	-	2/154/0	-	-	-	-	-	-	-
HTOL	Life Test, 140C	480 Hours	-	-	-	-	-	-	-	-	3/231/0	-
HTOL	Life Test, 125C	1000 Hours	-	-	1/77/0	1/77/0	1/77/0	-	3/231/0	-	-	-
LU	Latch-up, 25C	(per JESD78)	1/6/0	2/12/0	1/6/0	1/6/0	1/6/0	-	-	-	-	-
LU	Latch-up, 85C	(per JESD78)	1/6/0	2/12/0	-	-	-	-	-	-	-	-
LU	Latch-up, 125C	(per JESD78)	-	2/12/0	-	-	1/6/0	-	-	-	-	-
LU	Latch-up, 150C	(per JESD78)	-	1/6/0	-	-	-	-	-	-	-	-
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	1/Pass	2/Pass	-	1/Pass	-	-	-	3/Pass	3/Pass	3/Pass
MQ	Manufacturability (BUMP)	(per mfg. Site specification)	•	1/Pass	-	-	-	-	-	3/Pass	3/Pass	-
MQ	Manufacturability (Fab)	(per mfg. Site specification)	1/Pass	-	-	-	-	-	-	-	-	-
PD	Physical Dimensions	-	-	-	-	-	-	-	-	3/15/0	3/15/0	-
SBS	Bump-shear	-		-	-	-	-	3/108/0	-	5/150/0	5/150/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	-	-	-	-		-	-	
TC	Temperature Cycle, -55/125C	700 Cycles	-	-	1/77/0	-	-	-	-	3/231/0	3/231/0	3/231/0
UHAST	Unbiased HAST 130C/85%RH	96 Hours						3/228/0		3/231/0	3/231/0	3/231/0
VQR	Visual Quality Reliability Inspection	Post Temp Cycle	-	-	-	-	-	-	-	3/6/0	-	3/6/0
	he to manuar !	B										
VQR	Visual Quality Reliability Inspection	Post Unbiased HAST	-	-	-	-	-	-	-	3/6/0	-	3/6/0
BLR	Board Level Reliability, High Acceleration Shock 10kG	18 Cycles	-	-	-	-	-	-	-	3/99/0	3/99/0	-
BLR	Board Level Reliability, Random Vibration 5G 5-500Hz	30 Minutes	-	-	-	-	-	-	-	3/99/0	3/99/0	-
BLR	Board Level Reliability, Temp Cycle -40/85C	1000 Cycles	-	-	-	-	-	-	-	3/99/0	3/99/0	-
BLR	Board Level Reliability, Unbiased Temperature and Humidity, 85C/85%RH	1000 Hours	-	-	-	-	-	-	-	3/99/0	3/99/0	-

- QBS: Qual By Similarity
- Qual Device LM36274YFFR is qualified at LEVEL1-260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

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